# Shenzhen Crystal Technology Industrial Co.,Ltd

# **APPROVAL SHEET**

Approval Specification	Customer's Approval Certificate
то:	Please return this copy as a certification of your approval
Part No.:	Checked & Approved by:
Customer's Part No.:	Date:

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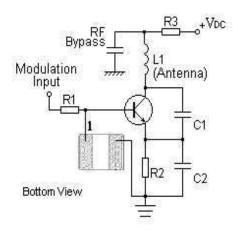
Prepared by:	
Checked by:	
Approved by:	

#### **Features**

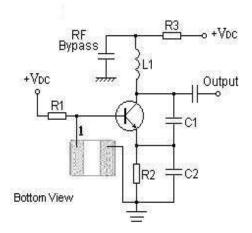
- 1-port Resonator
- CSP Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 2.00x1.60x0.90mm³
- Electrostatic Sensitive Device(ESD)

# **Application**

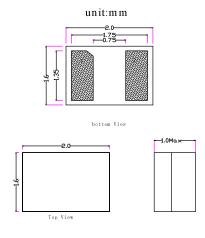
Typical Low-Power Transmitter Application



Typical Local Oscillator Application



# **Package Dimensions**



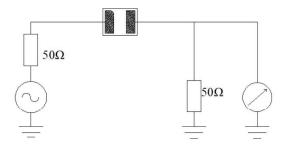
# **Pin Configuration**

1	Input/ Output
2	Output/ Input

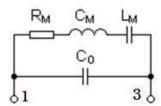
Marking

R434

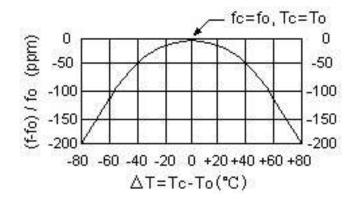
# **Test Circuit**



# **Equivalent LC Model**



# **Temperature Characteristics**



The curve shown above accounts for resonator contribution only and does not include LC component temperature contributions.

# **Performance**

# **Maximum Rating**

Item		Value	Unit
DC Voltage	V <sub>DC</sub>	10	V
Operation Temperature	Т	-40 ~ +85	$\mathbb{C}$
Storage Temperature	$T_{stg}$	-55 ~ +125	$\mathbb{C}$
RF Power Dissipation	Р	10	dBm

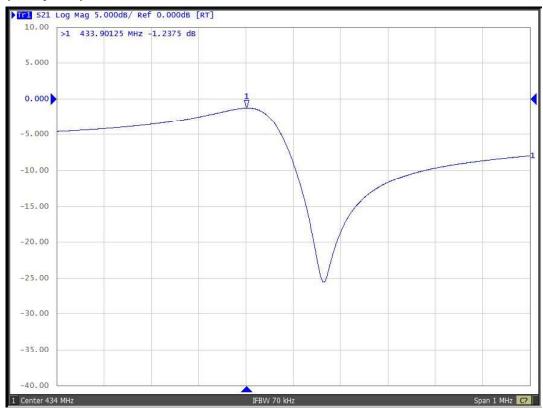
# **Electronic Characteristics**

Test Temperature:  $25^{\circ}C \pm 2^{\circ}C$ 

Terminating source impedance:  $50\Omega$ Terminating load impedance:  $50\Omega$ 

Item			Minimum	Typical	Maximum	Unit
Center Absolute Frequency		fc	433.820	433.920	434.020	MHz
Frequency	Tolerance from 433.920MHz	$\triangle f_c$		±100		KHz
Insertion Loss(r	nsertion Loss(min)			1.3	2.2	dB
Quality Factor Unloaded Q 50Ω Loaded Q		QU		12000		
		QL		1500		
	Turnover Temperature	T <sub>0</sub>	10	25	40	$^{\circ}$
Temperature Stability	Turnover Frequency	f <sub>0</sub>		f <sub>c</sub>		
_	Frequency Temperature Coefficient	FTC		0.032		ppm/℃
Frequency Aging	Absolute Value during the First Year			≤10		ppm/yr
DC Insulation Resistance between Any Two Pins			1.0			МΩ
	Motional Resistance	R <sub>M</sub>		12.196		Ω
RF Equivalent RLC Model	Motional Inductance	L <sub>M</sub>		183.82		μΗ
	Motional Capacitance	См		0.733		fF
	Static Capacitance	C <sub>0</sub>		2.23		pF

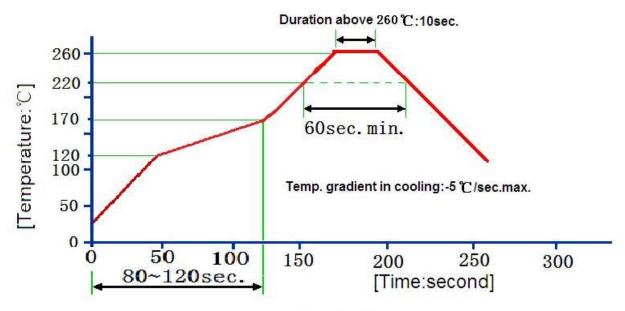
# **Frequency Response**



# Reliability (The SAW components shall remain electrical performance after tests)

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: 85℃±2℃, Duration: 250h, Recovery time: 2h±0.5h (2) Temperature: –55℃±3℃, Duration: 250h, Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60℃±2℃ , 90~95% RH
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min , Cycle time: 100 times , Recovery time : 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz  Amplitude:1.5mm  Directions: X,Y and Z  Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: 245 ℃ ±5 ℃ Duration: 3.0s5.0s  Depth: DIP2/3 , SMD1/5
7	Resistance to Soldering Heat	(1)Thickness of PCB:1mm , Solder condition: 260℃±5℃ , Duration: 10±1s (2)Temperature of Soldering Iron: 350℃±10℃ , Duration: 3~4s , Recovery time : 2 ± 0.5h

#### **Recommended Reflow Soldering Diagram**



Reflow cycles:3 cycles max.

#### **Notes**

- 1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
- 2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
- 3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- 4. Only leads of component may be soldered. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.